

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1.-3. (Cancelled)

4. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[1]] 17, wherein said first flexible wiring board has an input terminal region and an output terminal region.

5. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[1]] 17, wherein said surface-mounted component comprises at least one of second flexible wiring board includes at least one kind of surface-mounted part selected from among a flat-packaged LSI, a resistor, a capacitor, an inductance, a diode, a transistor, a quartz oscillator, and a connector.

6. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[3]] 17, wherein, in said first flexible wiring board, said power IC chip is connected to [[an]] a conductive layer through an anisotropic conductive film.

7. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[1]] 17, wherein, in said second flexible wiring board, said surface-mounted part is connected to an conductive layer through a solder layer.

8. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[1]] 17, wherein said interlayer contact portion comprises at least one of is constituted by an anisotropic conductive film [[or]] and solder.

9. (Currently Amended) The electro-optical device composite flexible wiring board according to Claim [[1]] 17, further comprising a third another flexible wiring board connected to said first flexible wiring board, said third another first flexible wiring board having an output terminal region.

10.-14. (Cancelled)

15. (Currently Amended) The electro-optical device according to Claim [[12]] 17, wherein said electro-optical material includes panel is an EL display panel having including, as an electro-optical material layer, an electroluminescence structure formed on said second substrate.

16. (Cancelled)

17. (New) An electro-optical device comprising:

a first substrate;

a second substrate opposite the first substrate, the second substrate having a projected portion that projects outward further than an edge of the first substrate;

an electro-optical material disposed between the first substrate and the second substrate;

a driver IC chip mounted on the projected portion of the second substrate using Chip On Glass technology;

a wiring junction region provided on the projected portion of the second substrate, the wiring junction region being electrically connected to the IC chip;

a first flexible wiring board mounted to the projected portion of the second substrate and in electrical connection with the wiring junction region;

a power IC chip mounted on the first flexible wiring board;

a second flexible wiring board disposed on the first flexible wiring board at a position inboard of the first flexible wiring board;

an interlayer contact portion that electrically connects the first flexible wiring board and the second flexible wiring board together; and

a surface-mounted component mounted on the second flexible wiring board.